

LNJ812R83RA

Ultra High Bright Surface Mounting Chip LED

InGaAlP TSS Type

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

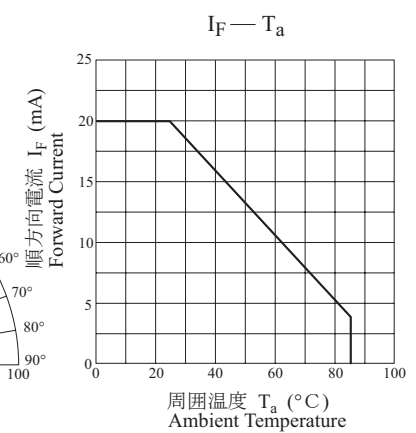
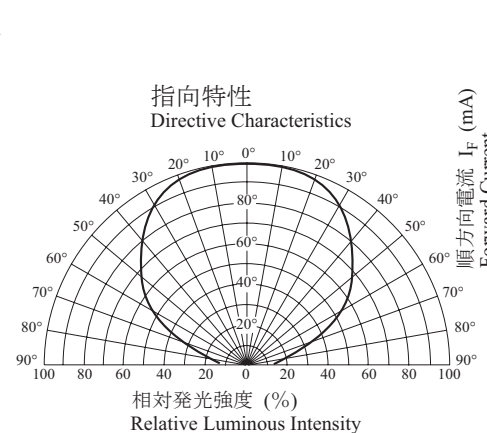
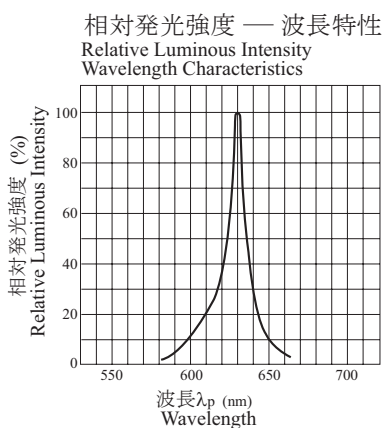
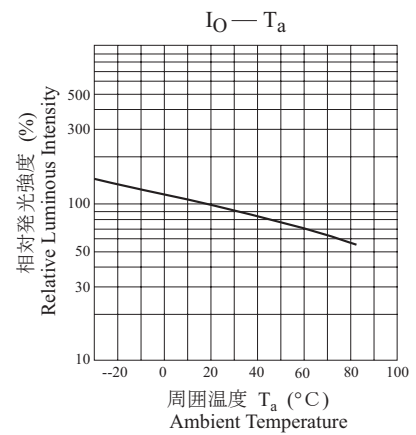
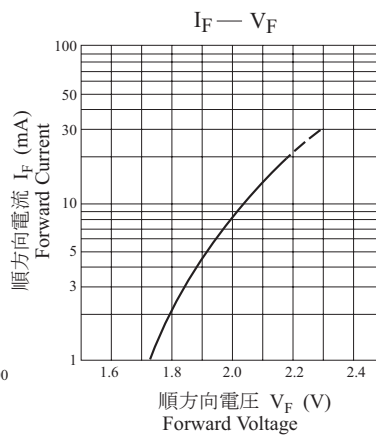
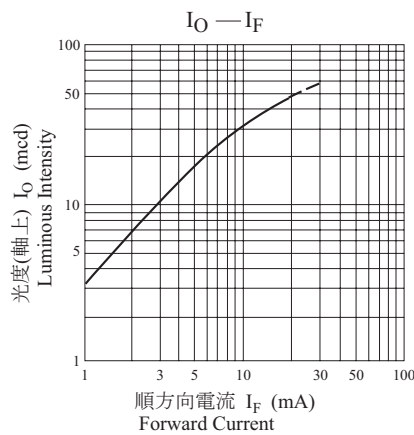
Parameter	Symbol	Rating	Unit
Power dissipation	P_D	55	mW
Forward current	I_F	20	mA
Pulse forward current	I_{FP}	60	mA
Reverse voltage	V_R	4	V
Operating ambient temperature	T_{opr}	-30 to +85	$^\circ\text{C}$
Storage temperature	T_{stg}	-40 to +100	$^\circ\text{C}$

■ Lighting Color / Lens Color

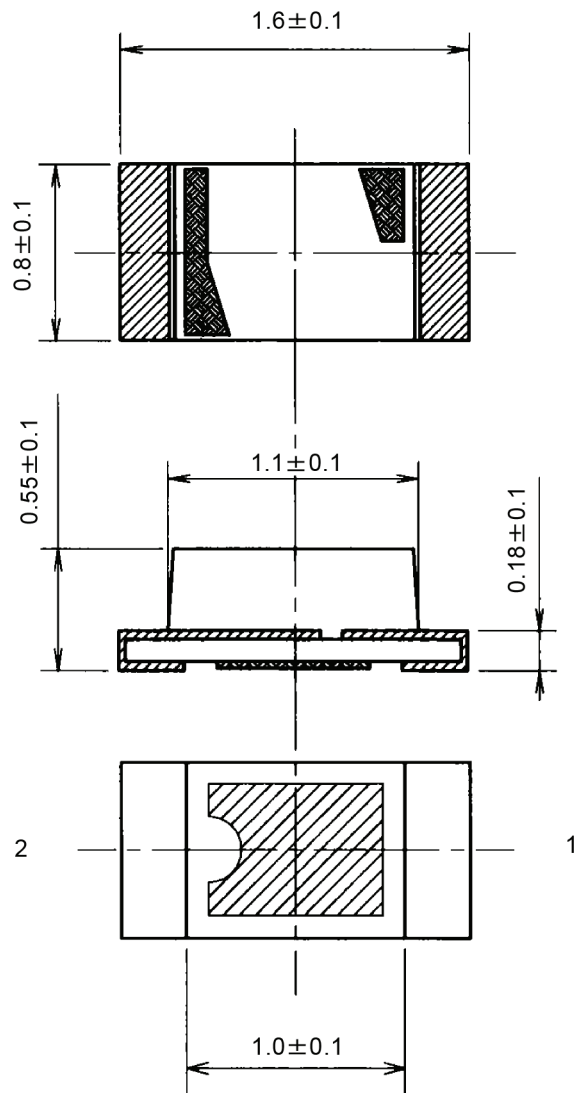
- Orange / Clear

■ Electro-Optical Characteristics $T_a = 25^\circ\text{C}$

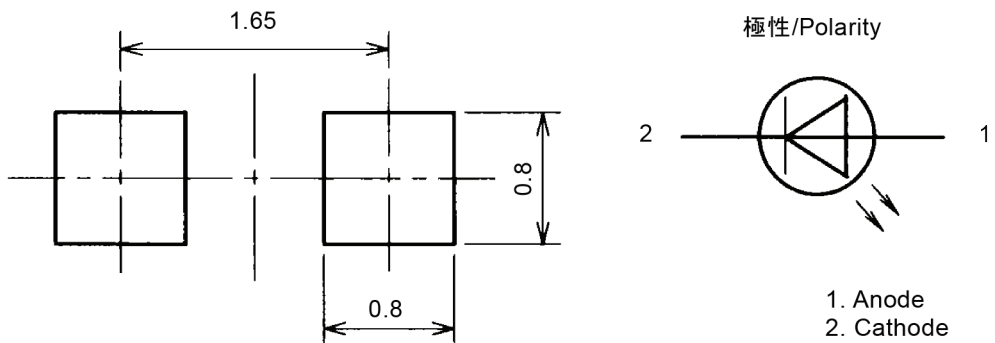
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	I_O		17	32		mcd
Forward current	I_F			10		mA
Forward voltage	V_F	$I_F = 10\text{ mA}$		2.03	2.5	V
Peak emission wavelength	λ_P	$I_F = 10\text{ mA}$		630		nm
Spectral half band width	$\Delta\lambda$	$I_F = 10\text{ mA}$		15		nm
Reverse current	I_R	$V_R = 4\text{ V}$			100	μA



■ Package (Unit: mm)



推奨パターン/Recommended Land Layout



1. Anode
2. Cathode

(注 1) パッケージ寸法については電極バリを含まない。
(Note1) Electrode projection is not included in the package dimensions.

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